

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Osamu Ozawa	12/13/2006
Toshio Sasaki	12/13/2006
Ryo Mori	12/13/2006
Takashi Kuraishi	12/13/2006
Yoshihiko Yasu	12/13/2006
Koichiro Ishibashi	12/15/2006
RECEIVING PARTY DATA	
Name:	Renesas Technology Corp.
Street Address:	4-1, Marunouchi 2-chome
City:	Chiyoda-ku, Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11614619
CORRESPONDENCE DATA	
Fax Number:	(703)610-8686
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-610-8620
Email:	ipdocketing@milesstockbridge.com
Correspondent Name:	Miles & Strockbridge P.C.
Address Line 1:	1751 Pinnacle Drive, Suite 500
Address Line 4:	McLean, VIRGINIA 22102
ATTORNEY DOCKET NUMBER:	XA-10725
NAME OF SUBMITTER:	Mitchel W. Shapiro

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**PATENT
REEL: 018669 FRAME: 0164**

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS TECHNOLOGY CORP., a corporation organized under the laws of Japan, located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS TECHNOLOGY CORP., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP.,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Osamu Ozawa</u> (Osamu OZAWA)	<u>13 / December / 2006</u>
2) <u>Toshio Sasaki</u> (Toshio SASAKI)	<u>13 / December / 2006</u>
3) <u>Ryo Mori</u> (Ryo MORI)	<u>13 / December / 2006</u>
4) <u>Takashi Kuraishi</u> (Takashi KURAISHI)	<u>13 / December / 2006</u>
5) <u>Yoshihiko Yasu</u> (Yoshihiko YASU)	<u>13 / December / 2006</u>
6) <u>Koichiro Ishibashi</u> (Koichiro ISHIBASHI)	<u>15 / December / 2006</u>
7) _____	_____
8) _____	_____